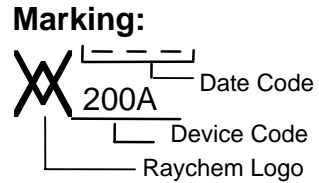
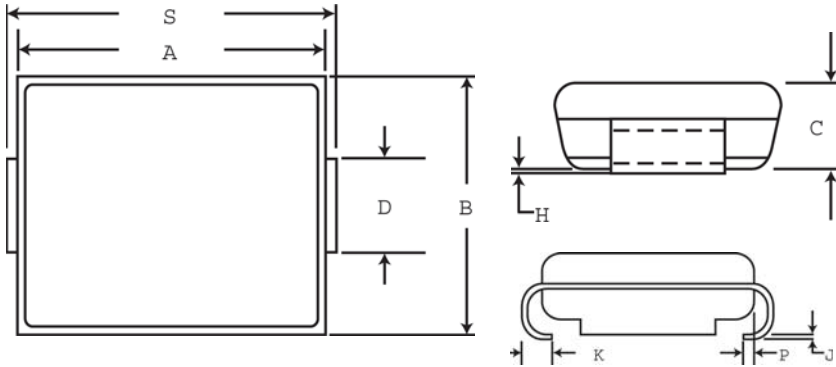


**Specification Status: RELEASED**

**PHYSICAL DESCRIPTION**



|      | A       |         | B       |         | C       |         | D**     |         | H       |         | J       |         | K       |         |
|------|---------|---------|---------|---------|---------|---------|---------|---------|---------|---------|---------|---------|---------|---------|
|      | MIN     | MAX     | MIN     | MAX     | MIN     | MAX     | MIN     | MAX     | MIN     | MAX     | MIN     | MAX     | MIN     | MAX     |
| mm:  | 4.06    | 4.57    | 3.30    | 3.81    | 1.90    | 2.41    | 1.96    | 2.11    | 0.051   | 0.152   | 0.15    | 0.30    | 0.76    | 1.27    |
| in*: | (0.160) | (0.180) | (0.130) | (0.150) | (0.075) | (0.095) | (0.077) | (0.083) | (0.002) | (0.006) | (0.006) | (0.012) | (0.030) | (0.050) |

|      | P       | S       |         |
|------|---------|---------|---------|
|      | REF     | MIN     | MAX     |
| mm:  | 0.51    | 5.21    | 5.59    |
| in*: | (0.020) | (0.205) | (0.220) |

\*Rounded off approximation  
\*\* D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P

**Other Physical Characteristics**

- Form Factor: SMB (Surface Mount, JEDEC DO-214AA Package)
- Lead Material: Matte Tin Finish
- Encapsulation Material: Epoxy, meets UL94 V-0 requirements
- Solderability: per MIL-STD-750, Method 2026
- Solder Heat Withstand: per MIL-STD-750, Method 2031
- Solvent Resistance: per MIL-STD-750, Method 1022
- Mechanical Shock: per MIL-STD-750, Method 2016
- Vibration: per MIL-STD-750, Method 2056

Tape and Reel packaging per EIA 481-1

- Agency Recognition: UL
- Precedence: This specification takes precedence over documents referenced herein.
- CAUTION: Operation beyond the rated voltage or current may result in rupture, electrical arcing or flame.

**Materials Information**

- RoHS Compliant
- ELV Compliant

Directive 2002/95/EC Compliant

Directive 2000/53/EC Compliant

OBSOLETE  
NOT the LATEST  
REVISION

**DEVICE RATINGS @ 25° C (Both Polarities)**

| Parameter  | Symbol   | Value      | Units                    |
|--|--|------------|--------------------------|
| Repetitive off-State Voltage, Maximum at $I_D = 5 \mu A$   | VDM  | 200        | V                        |
| Non-Repetitive Peak<br>Impulse Current   | TELCORDIA GR-1089 CORE 10x1000 $\mu s$               | 50         | A                        |
|  | TIA-968 lightning Type A Metallic 10/560 $\mu s$     | 70         | A                        |
| Double exponential<br>Waveform   | TIA-968 lightning Type A Longit. 10/160 $\mu s$      | 100        | A                        |
|  | Telcordia GR-1089 Intrabuilding 2/10 $\mu s$         | 150        | A                        |
| (Notes 1 and 2)  | IEC61000-4-5 (Voc 1.2/50us) 8/20 $\mu s$             | 150        | A                        |
|  | ITU-T K.20/K.21 (Voc 10/700us) 5/310 $\mu s$         | 90         | A                        |
|  | TIA-968 lightning Type B (Voc 9/720us) 5/320 $\mu s$ | 90         | A                        |
| Critical Rate of Rise of On-State Current<br>Powered Pulse Amplifier, C=30 $\mu F$ , V=600V<br>Maximum 2x10 $\mu sec$ waveform, $V_{OC}=750V$ , $I_{SC}=150A$ peak | di/dt<br>di/dt                                       | 500<br>110 | A/ $\mu s$<br>A/ $\mu s$ |

**DEVICE THERMAL RATINGS**

| Parameter   | Symbol | Value      | Units |
|---|--------|------------|-------|
| Storage Temperature Range                                       | TSTG   | -55 to 150 | °C    |
| Operating Temperature Range<br>Blocking or conducting state     | TA     | -40 to 125 | °C    |
| Overload Junction Temperature<br>Maximum; Conducting state only | TJ     | +150       | °C    |
| Maximum Lead Temperature for Soldering Purpose; for 10 seconds  | TL     | +260       | °C    |

**ELECTRICAL CHARACTERISTICS Both polarities ( $T_J$  @ 25°C unless otherwise noted)**

| Characteristics   | Symbol   | Min  | Typ   | Max   | Units      |
|---|----------|------|-------|-------|------------|
| Breakover Voltage (+25°C)<br>(dv/dt = 0.4kV/ $\mu sec$ , $I_{SC}=900mA$ , $V_{DC} = 500V$ (both polarities))              | VBO      | ---- | 260   | 320   | V          |
| Breakover Voltage Temperature Coefficient   | dVBO/dTJ | ---- | 0.1   | ----- | %/°C       |
| Off-State Current (VD1=50V)   | ID1      | ---- | ----- | 2.0   | $\mu A$    |
| (VD2=VDM)   | ID2=IDM  | ---- | ----- | 5.0   | $\mu A$    |
| On-State Voltage (IT=1A)<br>(PW ≤ 300 $\mu sec$ , Duty Cycle ≤ 2% (Note 2))   | VT       | ---- | ----- | 4.0   | V          |
| Breakover Current   | IBO      | ---- | ----- | 800   | mA         |
| Holding Current (Note 2)  | IH       | 150  | ----  | ----  | mA         |
| Peak Onstage Surge Current<br>(Measured @ 60Hz, 1 cycle, 600V)  | ITSM     | 22   | ----  | ----  | A          |
| Critical Rate of Rise of Off-State Voltage<br>(Linear waveform, $V_D = 0.8 \times$ Rated $V_{BO}$ , $T_J = +25^\circ C$ ) | dv/dt    | 2000 | ----  | ----  | V/ $\mu s$ |
| Capacitance (f=1.0 Mhz, 50V $_{DC}$ bias, 1Vrms)  | C1       | ---- | 18    | ----  | pF         |
| (f=1.0 Mhz, 2V $_{DC}$ bias, 1Vrms)   | C2       | ---- | 35    | ----  | pF         |

Note 1. Allow cooling before test second polarity

Note 2. Measured under pulse conditions to reduce heating

**VOLTAGE-CURRENT CHARACTERISTIC**
